

STM32WL_QFN48_IPD_2Layers_HighPower

MB1874_HP

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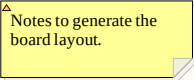
- Sheet 1: Project overview (this page)
- Sheet 2: STM32WL_QFN48_RefBoard_IPD_2Layers_HP

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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STM32WL_QFN48_RefBoard_IPD_2Layers_HP:SchDoc

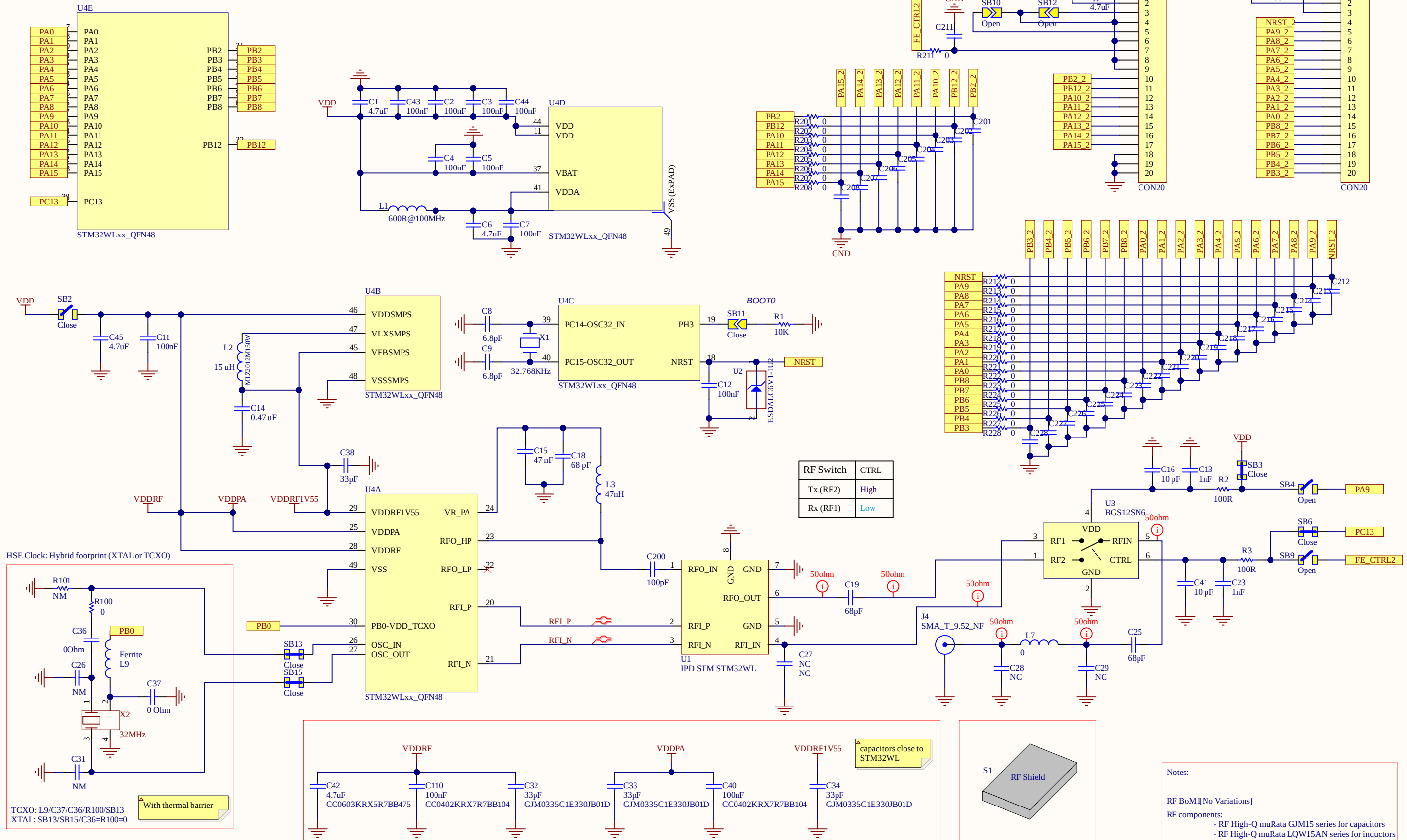


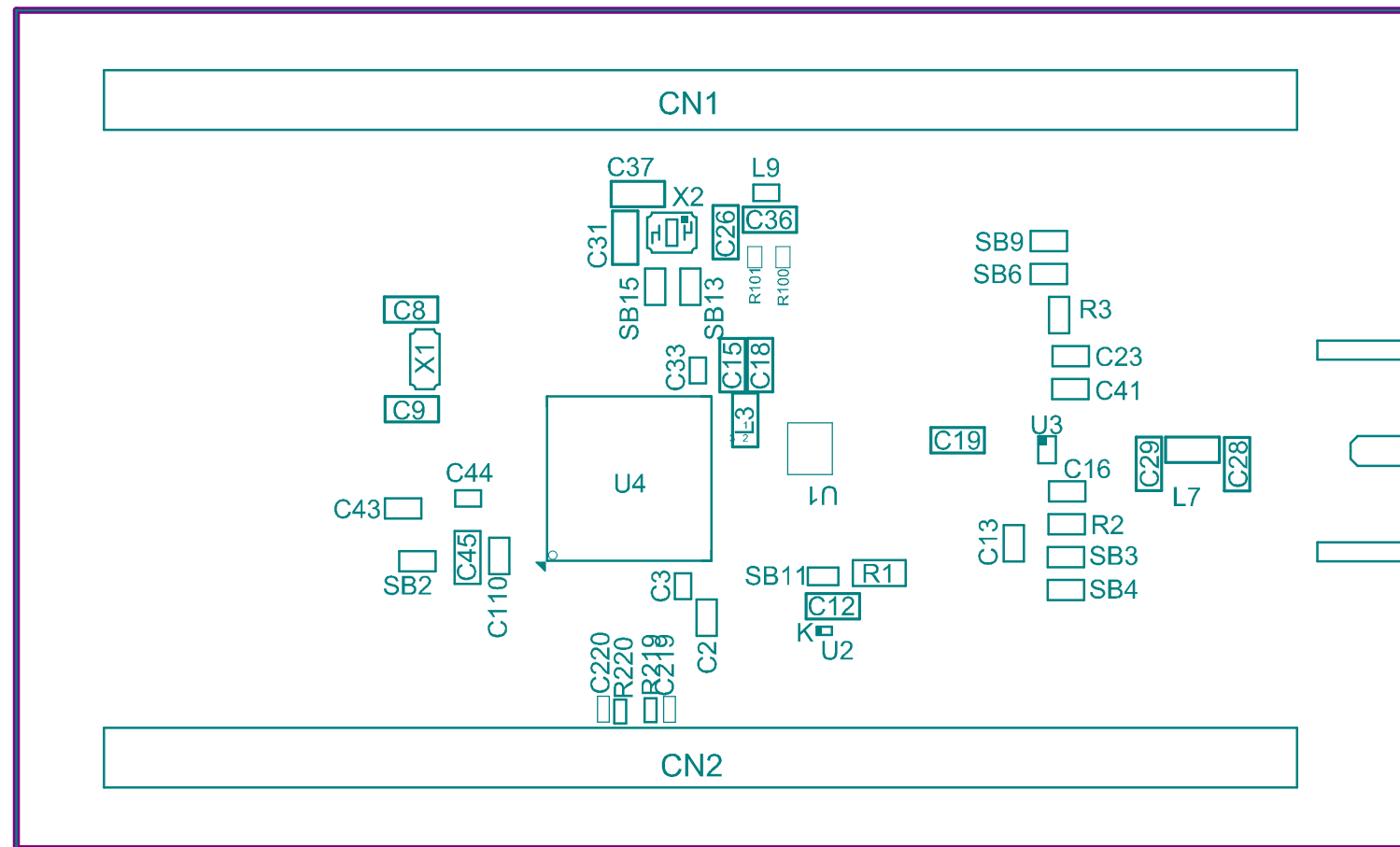
Title: Schematic sheet title to update		
Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Variant: [No Variations]		
Revision: A-	Reference: MB1874_HP	
Size: A4	Date: 20/07/2022	Sheet: 1 of 2



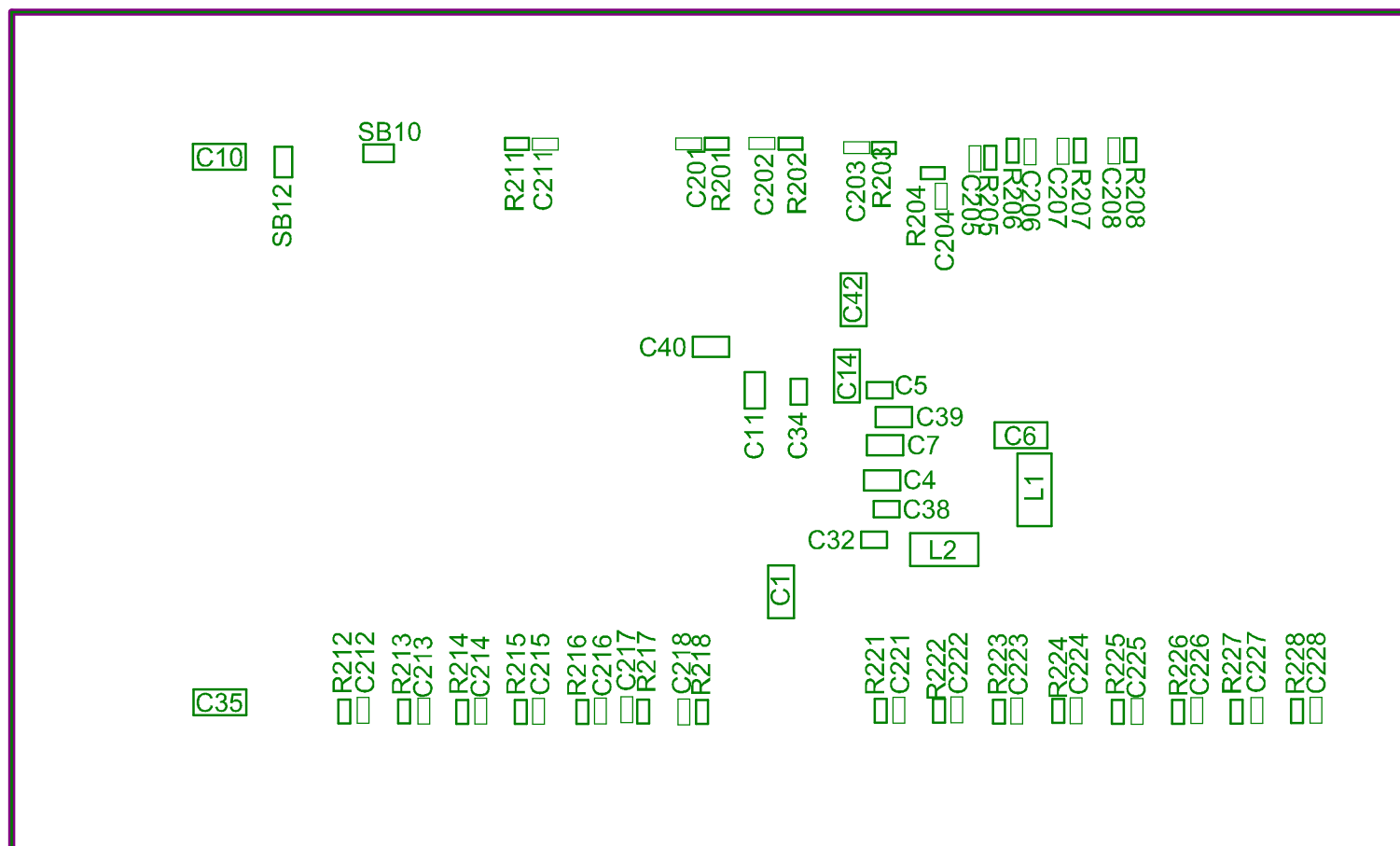
STM32WL QFN 2 Layers IPD - High Power Mode - Reference Board

Connectors from daughter board (TOP LAYER)





Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Top Assembly	Gerber: .GM14	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	



Project: STM32WL_QFN48_IPD_2Layers_HighPower		
Layer: Bottom Assembly	Gerber: .GM15	
Variant: [No Variations]	Ref: MB1874_HP	
Date: 20/07/2022	Rev: A	

